

WIRE BONDING METHOD AND APPARATUS

ABSTRACT OF THE DISCLOSURE

A process and apparatus are described for wire bonding circuit devices of large scale integrated design. The
5 bonding process employs a capillary tool that applies heat and pressure to the wires in order to bond them to the circuit device. The circuit device, or pad, is supported upon a closed woven, fiberglass mesh, which supports the circuit device during the bonding process.

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